



Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: G-0110-06	DATE: 12/14/2001	<b>MEANS OF DISTINGUISHING CHANGED DEVICES:</b> <input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input checked="" type="checkbox"/> Others, alpha suffix "F" in Assembly lot number.
Product Affected: Package Family TSSOP, TQFP, TSOP		
Date Effective: March 15, 2002		

Contact: Geoffrey Cortes Title: Manager, Corporate Quality & Reliability Phone #: (408) 492-8321 Fax #: (408) 727-2328 E-mail: <a href="mailto:gcortes@idt.com">gcortes@idt.com</a>	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No  Samples: Available upon request.
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**DESCRIPTION AND PURPOSE OF CHANGE:**

Die Technology  
 Wafer Fabrication Process  
 Assembly Process  
 Equipment  
 Material IDT will be qualifying the new EME-7351LP and EME-S351LP mold compound materials from Sumitomo.  
 Testing Once qualified, IDT will add these mold compound materials as qualified materials for TSOP,  
 Manufacturing Site TSSOP and TQFP packages.  
 Data Sheet  
 Other

**RELIABILITY/QUALIFICATION SUMMARY:**

Qualification testing will verify that there is no change to the product reliability.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <b><i>Approval for shipments prior to effective date.</i></b>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

**CUSTOMER COMMENTS:** \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_ DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: G-0110-06

**PCN Summary**

**PCN Type:** Mold compound materials, Sumitomo EME-7351LP and EME-S351LP.

**Data Sheet Change** No

**Detail of Change** Additional mold compound materials.

Description	Current	Add
Mold Compound	Shinetsu KMC 184, Shinetsu KMC 184VA, Sumitomo 6300, Sumitomo 7320 series	Sumitomo 7351, Sumitomo S351 series

Package Family	Package Type	Top Mark Designator	Package Family	Package Type	Top Mark Designator	Package Family	Package Type	Top Mark Designator
TSSOP	PA48	PA	TQFP	PK100	PF, TF	TSOP	PH44	PH
	PA56	PA		PK128	PRF, TF, PF			
				PN64	PF			
				PN80	PF			
				PN100	PF			

Note: Only the packages with the above top mark designator are impacted by this change.

**Conversion schedule (Estimated)**

	Sample Availability Beginning	Production Shipments Beginning
TSSOP	1/2/2002	2/18/2002
TQFP	1/2/2002	3/18/2002
TSOP	12/3/2001	2/18/2002
TSOP (Low Alpha)	2/1/2002	4/1/2002

Please contact your local field sales representative for sample availability and production shipments.









# SUMITOMO BAKELITE

## SUMIKON<sup>®</sup>

EME-7351LP

BI-PHENYL RESIN  
JEDEC LEVEL 1  
LOW CTE  
LONG SPIRAL FLOW

### EME-7351LP

#### TYPICAL PROPERTIES:

<u>ITEM</u>	<u>TEST METHOD</u>	<u>UNIT</u>	<u>VALUES</u>
SPIRAL FLOW	SB-U-03-003	cm	100
GEL TIME (at 175°C)	SB-U-03-005	sec	25
THERMAL EXPANSION $\alpha_1$	SB-U-02-002	$X 10^{-5} 1/^\circ C$	1.0
THERMAL EXPANSION $\alpha_2$	SB-U-02-002	$X 10^{-5} 1/^\circ C$	4.2
T <sub>g</sub>	SB-U-02-002	°C	135
THERMAL CONDUCTIVITY	SB-U-02-004	W/m •°C	$75 \times 10^{-2}$
FLEXURAL STRENGTH	SB-U-01-001	N/mm <sup>2</sup>	
(at 25°C)			200
(at 240°C)			22
FLEXURAL MODULUS	SB-U-01-002	$X 10^2$ N/mm <sup>2</sup>	
(at 25°C)			230
(at 240°C)			7.5
SPECIFIC GRAVITY	SB-U-03-018	-----	1.97
VOLUME RESISTIVITY	SB-U-00-004	$\Omega$ - cm	$1 \times 10^{13}$
(at 150°C)			
UL FLAME CLASS	SB-U-03-003	UL-94	V-0
WATER ABSORPTION	SB-U-03-002	% weight gain	0.17
(boiling, 24 h)			
EXTRACTED Na <sup>+</sup>	SB-U-04-043	ppm	1
EXTRACTED Cl <sup>-</sup>	SB-U-04-043	ppm	10

TYPICAL, NOT GUARANTEED PROPERTIES

#### MOLDING AND POST MOLD CURE CONDITIONS:

	<u>STANDARD</u>	<u>RANGE</u>
TRANSFER PRESSURE	$85 \times 10^6$ Pa	$70-120 \times 10^6$ Pa
MOLD TEMPERATURE	175°C	165-180°C
CURE TIME (C or A)#	A/70 sec	60-120 sec
POST-MOLD CURE TEMP	175°C	170-180°C
POST-MOLD CURE TIME	6 h	4-10h

#Conventional or Auto

rev. Nov.'00

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SUMITOMO BAKELITE CO., LTD.

Tennoz Parkside Building, 5-8 Higashi-Shinagawa, 2-Chome Shinagawa-ku, Tokyo 140, Japan

# SUMITOMO BAKELITE

## SUMIKON<sup>®</sup>

EME-S351LP

BI-PHENYL RESIN  
JEDEC LEVEL 1  
LOW CTE  
LOW ALPHA RAY

## EME-S351LP

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